

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

Supplier		User Part Number					
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		PMEG040V030EPE-Q Part Description					
		SMD package					
		Test Conditions	Duration	# Lots	# Quantity	# Rejects	
			TEST				
	Pre- and Post-Stress						
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
		JESD22-A113					
		Bake Tamb = 125 °C	24 hours				
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours				
# A1	Preconditioning	Reflow soldering	3 cycles	1514	64430	0	
		MIL-STD-750-1					
	HTRB	M1038 Method A					
	High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet					
# B1	Bias	reverse voltage ^[1]	1000 hours	206	9320	0	
	TC	JESD22-A104					
‡ A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	311	14080	0	
	UHAST	JESD22-A118					
# A3 or	Unbiased HAST	Tamb = 130 °C, RH = 85 %	— 96 hours	311	14080	0	
# A3 0 F	Official Control	· · · · · · · · · · · · · · · · · · ·					
	AC	JESD22-A102					
# A3 alt	Autoclave	Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)					
A3 alt	Autociave	Pressure = 203 KPa (29.7 psia)					
	H3TRB	JESD22-A101					
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of					
# A2 alt		rated reverse voltage ^{[1], [2]}	1000 hours	311	14080	0	
# AZ dit	. Imperator a reverse blus	MIL-STD-750 Method 1037	1000 110015	J11	1 1000		
	IOL	ton = toff, devices powered to insure ΔT_i =					
# A5	Intermittent Operating Life		1000 hours	312	14120	0	
, ,,,,	incommeter operating the	100 0.0. 10000 0,0.00	1000 110013	312	11120		
	RSH	JESD22-A111					
‡ C8	Resistance to Solder Heat		10 s	269	8070	0	
	SD					-	
£ C10	Solderability	J-STD-002		222	6660	0	
# C10	Solderability	J-STD-002		222	6660	0	

^[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

© 2024 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com

^[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.